

DALLAS

SEMICONDUCTOR

DS2264/DS2268

ADPCM Stik

T-75-11-37

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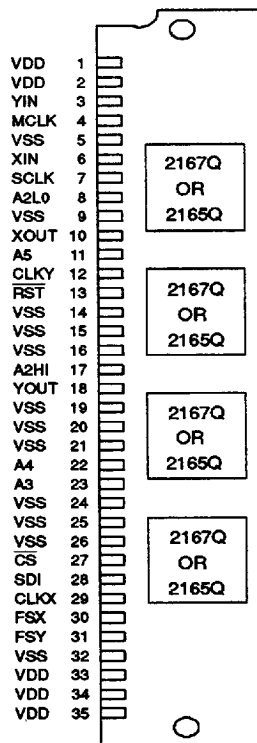
FEATURES

- Provides four channels (DS2264) or eight channels (DS2268) of parallel full-duplex ADPCM processing in a pre-fabricated, snap-in module
- Based on the DS2167Q or DS2165Q ADPCM Processor Chip which implements the T1.301 and CCITT G.721 recommendations
- Occupies only 2 square inches of board space
- Conforms to popular JEDEC standard 35 position single in-line connector
- Easily cascadable up to 64 full-duplex channels in multiples of four or eight
- Both A-law and μ -law compatible
- Utilizes serial interface port for microprocessor control of timeslot assignments
- Includes onboard buffers for all critical signals

ORDERING INFORMATION

4 channels with DS2167Q	DS2264
8 channels with DS2167Q	DS2268
4 channels with DS2165Q	DS2264 - EXP
8 channels with DS2165Q	DS2268 - EXP

PIN ASSIGNMENT



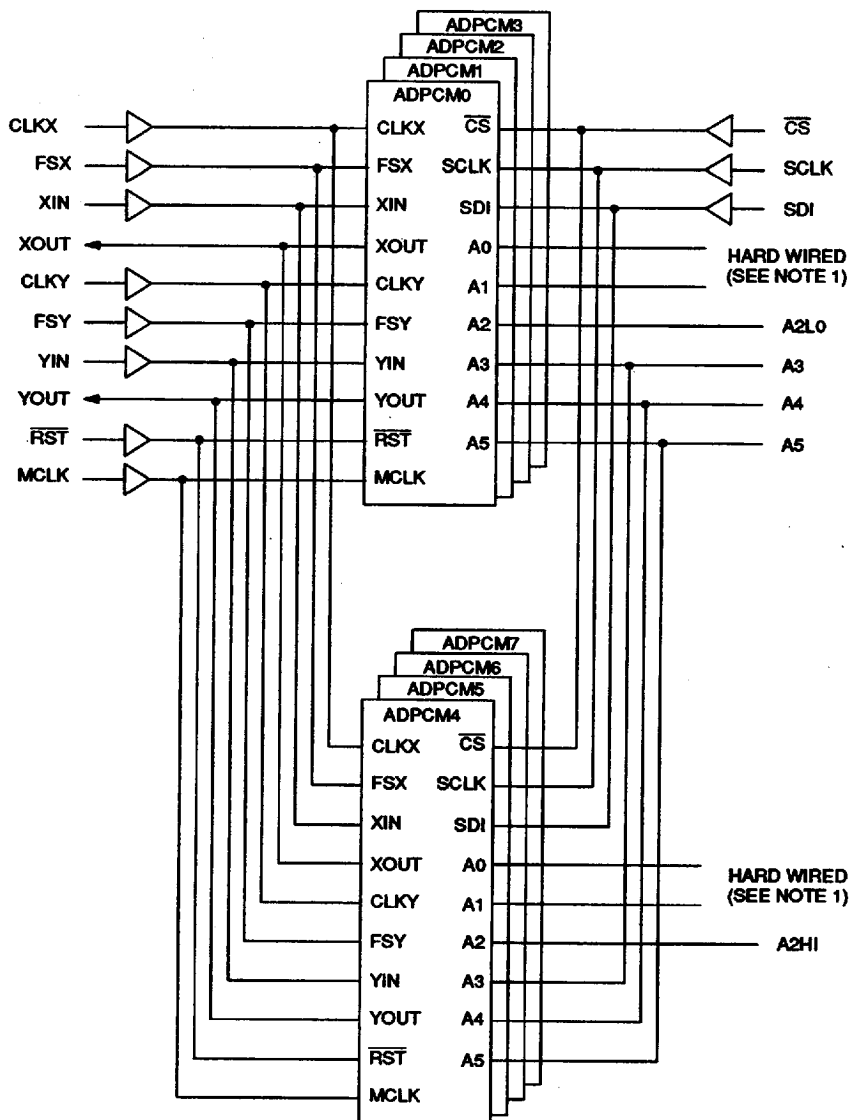
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DESCRIPTION

The DS2264 and DS2268 ADPCM Stiks are complete, pre-fabricated cards that perform either four or eight channels of full-duplex ADPCM processing. The ADPCM algorithm compresses 64Kbps voice data to either 32Kbps, 24Kbps, or 16Kbps. The DS2264 is only populated on one side and offers four channels while the

DS2268 is populated on both sides of the Stik and offers eight channels. Control of the Stiks is handled by an external microcontroller via a serial port. Both Stiks are based on the DS2167Q or DS2165Q ADPCM Processor Chips. Specific details on the DS2167Q and DS2165Q can be found in their respective data sheets.

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DS2264/DS2268 BLOCK DIAGRAM Figure 1



NOTES:

1. Pins A0 and A1 are configured as follows:

Processor	A1	A0
0 and 4	0	0
1 and 5	0	1
2 and 6	1	0
3 and 7	1	1

2. For the DS2264, processors 4 to 7 are not included and signal A2HI should be left open.

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PIN DESCRIPTION Table 1

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PIN	SYMBOL	TYPE	DESCRIPTION
1 2	V _{DD}	—	Positive Supply. 5.0 volts.
3	YIN	I	Y Data In. Sampled on falling edge of CLKY during selected time slots.
4	MCLK	I	Master Clock. 10 MHz clock for the ADPCM processing engine; may be asynchronous to SCLK, CLKX, and CLKY.
5	V _{SS}	—	Signal Ground. 0.0 volts.
6	XIN	I	X Data In. Sampled on falling edge of CLKX during selected time slots.
7	SCLK	I	Serial Data Clock. Used to write to the serial port.
8	A2LO	I	Address Bit 2. Defines address selection for the lower four channels. May be tied either high or low on the DS2264. Must be tied low on the DS2268.
9	V _{SS}	—	Signal Ground. 0.0 volts.
10	XOUT	O	X Data Output. Updated on rising edge of CLKX during selected time slots.
11	A5	I	Address Bit 5. Defines value for address bit 5.
12	CLKY	I	Y Data Clock. Data clock for the Y side PCM interface; must be synchronous with FSX.
13	RST	I	Reset. Active low. A high-low-high transition clears all internal registers, resets the algorithms, and idles the outputs of all the channels.
14 15 16	V _{SS}	—	Signal Ground. 0.0 volts.
17	A2HI	I	Address Bit 2. Defines address selection for upper four channels. Must be left open on the DS2264 and tied high on the DS2268.
18	YOUT	O	Y Data Output. Updated on rising edge of CLKY during selected time slots.
19 20 21	V _{SS}	—	Signal Ground. 0.0 volts.
22	A4	I	Address Bit 4. Defines value for address bit 4.
23	A3	I	Address Bit 3. Defines value for address bit 3.
24 25 26	V _{SS}	—	Signal Ground. 0.0 volts.
27	CS	I	Chip Select. Active low. Serial port select; must be low to write to the serial port.
28	SDI	I	Serial Data In. Data for onboard control registers; sampled on the rising edge of SCLK. LSB sent first.
29	CLKX	I	X Data Clock. Data clock for the X side PCM interface; must be synchronous with FSX.
30	FSX	I	X Frame Sync. 8 KHz frame sync for the X side PCM interface.
31	FSY	I	Y Frame Sync. 8 KHz frame sync for the Y side PCM interface.
32	V _{SS}	—	Signal Ground. 0.0 volts.
33 34 35	V _{DD}	—	Positive Supply. 5.0 volts.

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SYSTEM INTERFACE AND CONTROL

Both the DS2264 and DS2268 are designed to operate with an external microcontroller such as a DS5000 or an 8051/31. The microcontroller communicates to the ADPCM Stiks over a 3-wire serial port consisting of \overline{CS} , SCLK, and SDI. Data that is written to serial port can be either two or four bytes long. A 4-byte write consists of the Address/Command byte, the Control byte, the Input Time Slot byte, and the Output Time Slot byte. A 2-byte write only contains the Address/Command byte and the Control byte. Within the Address/Command byte, there

is an address field. Each ADPCM processor on the Stik monitors the serial port and looks for a match between its address (set by the configuration of the A0 to A5 pins) and the address specified in the Address/Command byte. If a match occurs, then either the next one or three bytes are accepted as configuration data. Complete details on the operation of the serial port can be found in the DS2167 and DS2165 data sheets. Details on the four configuration registers are shown in Figures 2 through 5.

ADDRESS/COMMAND BYTE Figure 2

(MSB)				(LSB)			
—	X/Y	A5	A4	A3	A2	A1	A0

SYMBOL	POSITION	NAME AND DESCRIPTION
—	ACB.7	Reserved; must be 0 for proper operation.
X/Y	ACB.6	X/Y Channel Select. 0 = update channel Y characteristics 1 = update channel X characteristics
A5	ACB.5	MSB of Device Address.
A4	ACB.4	
A3	ACB.3	
A2	ACB.2	
A1	ACB.1	
A0	ACB.0	LSB of Device Address.

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CONTROL REGISTER Figure 3

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(MSB)				(LSB)			
AS0	AS1	IPD	ALRST	BYP	U/A	AS2	CP/EX

SYMBOL	POSITION	NAME AND DESCRIPTION
AS0	CR.7	Algorithm Select 0. See table below.
AS1	CR.6	Algorithm Select 1. See table below.
IPD	CR.5	Idle and Power Down. 0 = channel enabled 1 = channel disabled (output 3-stated)
ALRST	CR.4	Algorithm Reset. 0 = normal operation 1 = reset algorithm for selected channel
BYP	CR.3	Bypass. 0 = normal operation 1 = bypass selected channel
U/A	CR.2	Data Format. 0 = A-law 1 = μ -law
AS2	CR.1	Algorithm Select 2. See table below.
CP/EX	CR.0	Channel Coding. 0 = expand (decode) selected channel 1 = compress (encode) selected channel

ALGORITHM SELECTED	AS2	AS1	AS0
64Kbps to/from 32Kbps	0	0	0
64Kbps to/from 24Kbps	1	1	1
64Kbps to/from 16Kbps	1	0	1

INPUT TIME SLOT REGISTER Figure 4

(MSB)				(LSB)			
—	—	D5	D4	D3	D2	D1	D0

SYMBOL	POSITION	NAME AND DESCRIPTION
—	ITR.7	Reserved; must be 0 for proper operation.
—	ITR.6	Reserved; must be 0 for proper operation.
D5	ITR.5	MSB of input time slot register.
D4	ITR.4	
D3	ITR.3	
D2	ITR.2	
D1	ITR.1	
D0	ITR.0	LSB of input time slot register.

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OUTPUT TIME SLOT REGISTER Figure 5

(MSB)				(LSB)			
—	—	D5	D4	D3	D2	D1	D0

SYMBOL	POSITION	NAME AND DESCRIPTION
—	OTR.7	Reserved; must be 0 for proper operation.
—	OTR.6	Reserved; must be 0 for proper operation.
D5	OTR.5	MSB of output time slot register.
D4	OTR.4	
D3	OTR.3	
D2	OTR.2	
D1	OTR.1	
D0	OTR.0	LSB of output time slot register.

DATA BUSSING

The DS2264 and DS2268 can be cascaded to process up to 64 full-duplex ADPCM channels. For example, eight DS2268s can be combined in parallel to achieve 64 channels. All of the common PCM interface signals (CLKX, FSX, XIN, XOUT, CLKY, FSY, YIN, YOUT) should be tied together. Also, the serial interface signals (SCLK, \overline{CS} , SDI) should be tied together. Every processor will be assigned a unique address via the A0 to A5 pins on the processor. Address pins A0 and A1 are already assigned for each ADPCM processor; the user selects A2 through A5. The address range for the processors on a single module is defined by the strapping of the A5, A4, A3, A2LO, and A2HI address control pins.

Each DS2264 occupies four consecutive address locations. The exact placement of this 4-address block is defined by the user via the address control pins. (See Table 2.) On the DS2264, the A2HI pin should be left open. Each DS2268 occupies eight consecutive address locations. (See Table 3.) On the DS2268, the A2HI pin should be tied to V_{DD} and the A2LO pin should be tied to V_{SS} . If the address control pins are tied so that each module in the stack has a unique range of addresses, then an external microcontroller will be able to select any processor in the group and configure it appropriately.

DS2264 ADDRESS STRAPPING Table 2

			4-Block Address Selected	
A5	A4	A3	A2LO = 0	A2LO = 1
0	0	0	0 through 3	4 through 7
0	0	1	8 through 11	12 through 15
0	1	0	16 through 19	20 through 23
0	1	1	24 through 27	28 through 31
1	0	0	32 through 35	36 through 39
1	0	1	40 through 43	44 through 47
1	1	0	48 through 51	52 through 55
1	1	1	56 through 59	60 through 63

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DS2268 ADDRESS STRAPPING Table 3

A5	A4	A3	8-Block Address Selected
0	0	0	0 through 7
0	0	1	8 through 15
0	1	0	16 through 23
0	1	1	24 through 31
1	0	0	32 through 39
1	0	1	40 through 47
1	1	0	48 through 55
1	1	1	56 through 63

SYSTEM RESET

A system reset may be initialized with a high-low-high transition on the $\overline{\text{RST}}$ pin. This action clears all of the internal registers, resets the ADPCM algorithms, and places the processors in idle (outputs 3-stated). On system power-up, the $\overline{\text{RST}}$ pin should be held low for at least 1 ms after the Master Clock (MCLK) has stabilized to assure proper initialization. Use of a DS1231 or DS1232 will automatically generate a reset when power

is applied. Please see the Dallas Semiconductor Data Book for more information on the DS1231 and DS1232.

STIK CONNECTORS

The DS2264 and DS2268 are designed to connect into a standard 35-pin SIMM connector with a pin spacing pitch of 0.100 inches. Both vertical and inclined connectors are available from connector vendors such as AMP and Molex. Table 4 lists two such connectors.

35-PIN SIMM CONNECTORS FOR DS2264/DS2268 Table 4

Description	Vendor	Part Number
Vertical upright	AMP	821828-3
Low profile, 25 degree angle	Molex	15-46-0385

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ABSOLUTE MAXIMUM RATINGS*

Voltage on any Pin Relative to Ground

-1.0V to +7.0V

Operating Temperature

0°C to 70°C

Storage Temperature

-55°C to +125°C

* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

(0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Logic 1	V_{IH}	2.0		$V_{CC}+0.3$	V	
Logic 0	V_{IL}	-0.3		+0.8	V	
Supply	V_{DD}	4.5		5.5	V	

CAPACITANCE(t_A=25°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	C_{IN}			20	pF	
Output Capacitance	C_{OUT}			40 80	pF pF	4 5

DC ELECTRICAL CHARACTERISTICS(0°C to 70°C; $V_{DD}=5V \pm 10\%$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Operating Current	I_{DDA}			175 280	mA mA	1,2,4 1,2,5
Standby Current	I_{DDPD}			50 50	mA mA	1,2,3,4 1,2,3,5
Input Leakage	I_I	-40.0		+40.0	μA	
Output Leakage	I_{IO}	-4.0 -8.0		+4.0 +8.0	μA μA	4,6 5,6
Output Current (2.4V)	I_{OH}	-1.0			mA	
Output Current (0.4V)	I_{OL}	+4.0			mA	

NOTES:

1. CLKX = CLKY = 1.544 MHz; MCLK = 10 MHz.
2. Outputs open; inputs swinging full supply levels.
3. All channels of all processors programmed to idle (IPD = 1).
4. For DS2264 only.
5. For DS2268 only.
6. XOUT and YOUT 3-stated.

PCM INTERFACE AC ELECTRICAL CHARACTERISTICS(0°C to 70°C; $V_{DD}=5V \pm 10\%$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
CLKX, CLKY Period	t_{pXY}	244		5208	ns	4
CLKX, CLKY Pulse Width	t_{WXYL} t_{WXYH}	100			ns	
CLKX, CLKY Rise Fall Times	t_{RXY} t_{FXY}		10	20	ns	
Hold Time from CLKX, CLKY to FSX, FSY	t_{HOLD}	0			ns	1
Setup Time from FSX, FSY High to CLKX, CLKY Low	t_{SF}	50			ns	1
Hold Time from CLKX, CLKY Low to FSX, FSY Low	t_{HF}	100			ns	1
Setup Time for XIN, YIN to CLKX, CLKY Low	t_{SD}	50			ns	1
Hold Time for XIN, YIN to CLKX, CLKY Low	t_{HD}	50			ns	1
Delay Time from CLKX, CLKY to Valid XOUT, YOUT	t_{dXYO}	10		150	ns	2
Delay Time from CLKX, CLKY to XOUT, YOUT 3-stated	t_{dXYZ}		150		ns	1,2,3

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NOTES:

1. Measured at $V_{IH} = 2.0V$, $V_{IL} = 0.8V$, and 10 ns maximum rise and fall times.
2. Load = 150 pF + 2 LSTTL loads.
3. For LSB of PCM or ADPCM byte.
4. Maximum width of FSX and FSY is one CLKX or CLKY period.

MASTER CLOCK/RESET AC ELECTRICAL CHARACTERISTICS(0°C to 70°C; $V_{DD}=5V \pm 10\%$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
MCLK Period	t_{PM}		100		ns	1
MCLK Pulse Width	t_{WMH} t_{WML}	45	50	55	ns	
MCLK Rise/Fall Times	t_{RM} , t_{FM}			10	ns	
RST Pulse Width	t_{RST}	1			ms	

NOTE:

1. MCLK = 10 MHz \pm 500 ppm.

SERIAL PORT AC ELECTRICAL CHARACTERISTICS

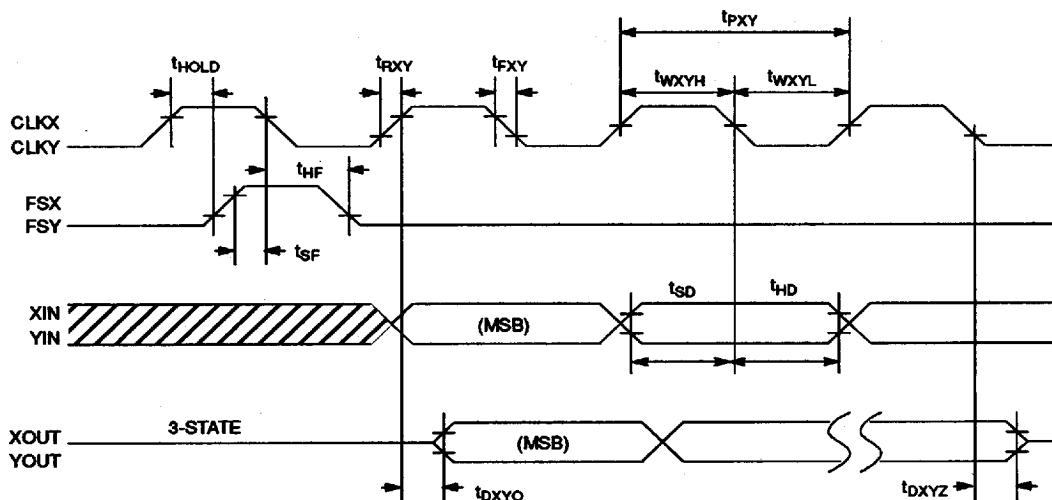
(0°C to 70°C; $V_{DD}=5V \pm 10\%$)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
SDI to SCLK Set Up	t_{DC}	55			ns	1
SCLK to SDI Hold	t_{CDH}	55			ns	1
SCLK Low Time	t_{CL}	250			ns	1
SCLK High Time	t_{CH}	250			ns	1
SCLK Rise and Fall Time	t_R, t_F			100	ns	1
\overline{CS} to SCLK Set Up	t_{CC}	50			ns	1
SCLK to \overline{CS} Hold	t_{CCH}	250			ns	1
\overline{CS} Inactive Time	t_{CWH}	250			ns	1
SCLK Set Up to \overline{CS} Falling	t_{SCC}	50			ns	1

NOTE:

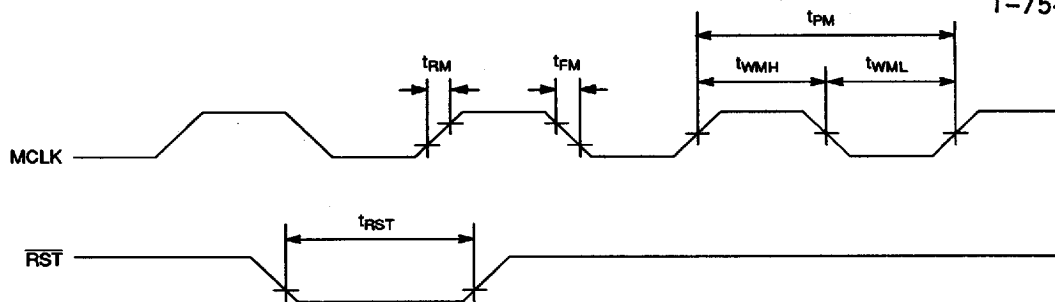
1. Measured at $V_{IH} = 2.0V$, $V_{IL} = 0.8V$, and 10ns maximum rise and fall times.

PCM INTERFACE AC TIMING DIAGRAM Figure 6

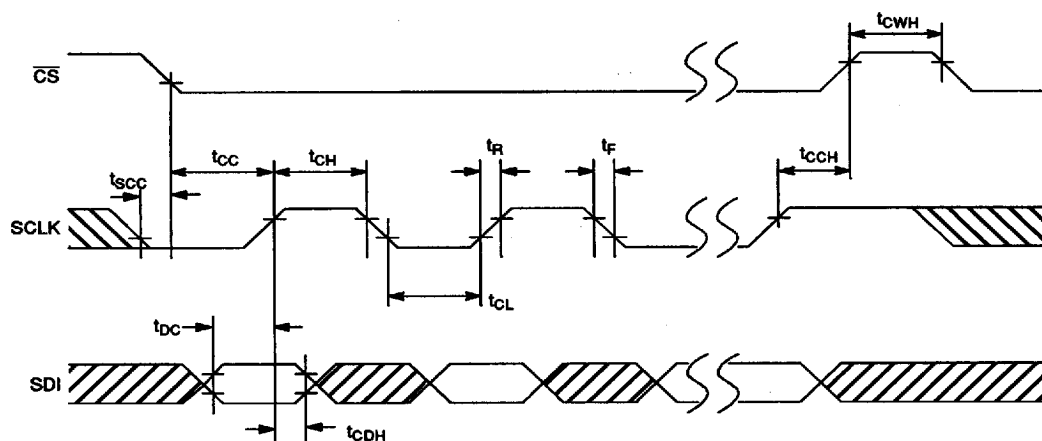


MASTER CLOCK/RESET AC TIMING DIAGRAM Figure 7

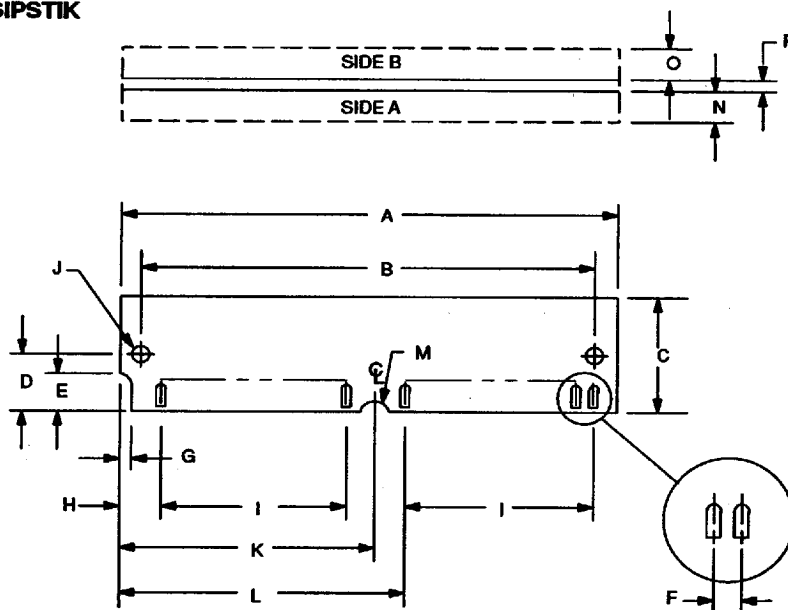
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SERIAL PORT AC TIMING DIAGRAM Figure 8

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**DS2264/DS2268 ADPCM STIK
35-PIN SIPSTIK**

PKG	35-PIN	
	MIN	MAX
A IN.	3.995	4.005
B IN.	3.729	3.739
C IN.	0.795	0.805
D IN.	0.395	0.405
E IN.	0.245	0.255
F IN.	0.100 BSC	
G IN.	0.075	0.085
H IN.	0.295	0.305
I IN.	2.900 BSC	
J IN.	0.120	0.130
K IN.	0.000	0.000
L IN.	0.000	0.000
M IN.	0.000	0.000
N IN.		0.230
O IN.		0.230
P IN.		0.054